Attorney Docket No. 1572.1252

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Appli	cation of:			
Se-Young JANG	et al			
Application No.:		Group Art Unit:		
Filed: April 13, 20	04	Examiner:		
For: SURFACE	E-MOUNTING METHOD OF SEM	ICONDUCTOR CHIP ON PCB		
	INFORMATION DISCLOS	SURE STATEMENT		
Commissioner for PO Box 1450 Alexandria, VA 22				
Sir:				
provided certain i subject U.S. pate	nformation that the Examiner may	ovisions of 37 CFR § 1.56, there is hereby consider material to the examination of the the Examiner make this information of record bject application.		
1. Er	closures accompanying this Infor	mation Disclosure Statement are:		
1a. ⊠ 1b. ⊠ 1c. ☐ 1d. ☐ 1e. ⊠	Copies of IDS citations. An English language copy of sapplication or a PCT Internation English language translation (ceach non-English language put Explanations of Relevancy of F	complete or relevant portion(s)) attached to		
2. 🛭 Ir u	accordance with 37 CFR § 1.98, nderstood to be the relevance of e	a concise explanation of what is presently each non-English language publication is		
2a. 🗀	enclosed "English-language verindicates the degree of relevar 609, Minimum Requirements f A(3): Concise Explanation of Feb. 2000.)	is 2a, 2b, 2c and/or 2d) ish language publications were cited on the ersion of the search report or action which nce found by the foreign office". (See MPEP or an Information Disclosure Statement, Part Relevance, pp. 600-100 to 600-101, Rev. 1,		
2b	set forth in the application.			

	lish language translation (complete or relevant each non-English language publication. 1(e), hereto.				
3. No admission is made that the information cited in this Statement is, or is considered to be, material to patentability nor a representation that a search has been made (other than search report(s) from a counterpart foreign application or a PCT International Search Report, if submitted herewith). 37 CFR §§ 1.97(g) and (h).					
Respectfully submitted,					
STAAS & HALSEY LLP					
Dated: April 13, 2004 1201 New York Ave., N.W., Suite 700 Washington, D.C. 20005 Telephone: (202) 434-1500 Facsimile: (202) 434-1501	By: Gene M. Garner II Registration No. 34,172				

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FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO.	APPLICATION NO.		
1572.1252			
FIRST NAMED INVENTOR			
Se-Young JANG et al			
FILING DATE	GROUP ART UNIT		

April 13, 2004

LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

ILS PATENT DOCUMENTS

U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
	AA	2002/0089067	7/11/02	Crane et al.			
	АВ	2003/0038342	2/27/03	Standing			
	AC	2003/0045028	3/6/03	Tsao et al.			
	AD	5,710,071	1/20/98	Beddingfield et al.			
	AE	6,201,301	3/13/01	Hoang			
	AF	6,507,119	1/14/03	Huang et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB- CLASS	TRANS	NO
AG	10-0326108	2/14/02	Korea				Х
 AH	2002-63628	8/3/02	Korea				Х
Al	2002-33944	5/8/02	Korea				Х
AJ	2002-43755	6/12/02	Korea				Х
 AK	2002-91916	10/23/01	Korea				Х
AL	2002-14861	2/20/03	Korea				Х
AM	2002-44577	6/15/02	Korea				х
AN	2002-28454	4/8/03	Korea				Х
AO	1 256 387	11/13/02	European				

01	THER R	EFERENCES (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES	<u>, ETC.)</u>	
				LATION NO
	AM			
EXAMINER		DATE CONSIDERED	<u>-</u>	

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

ATTACHMENT 1(e)

OF REFERENCES

ATTORNEY DOCKET NO. APPLICATION NO.		
1572.1252		
FIRST NAMED INVENTOR		
Se-Young JANG et al		
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April 13, 2004		

Korean Patent No. 10-326108 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-63628 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-33944 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-43755 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-91916 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-14861 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-44577 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.

Korean Publication No. 2002-28454 is generally related to a Method of Surface-Mounting Semiconductor Chip on PCB.